Cypress Semiconductor Corporation – An Infineon Technologies Company
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PRODUCT CHANGE NOTIFICATION

PCN: PCN211205 **Date:** March 29, 2021

Subject: Assembly Site and Bill of Materials Information for Select Industrial-Grade 32Mb MoBL® SRAM Products

To: PCN DIGIKEY SUPPLIER
DIGIKEY
DigiKey.SupplierInfo@digikey.com

Change Type: Major

Description of Change:
The purpose of this notification is to communicate the assembly site and Bill of Materials information for the 32Mb MoBL® SRAM products in 48-Ball BGA and 48-Lead TSOP I packages assembled using the die from UMC's 65nm wafer fab.

Cypress announces the qualification of Cypress Bangkok, Thailand (BKK, 229 Moo 4 Changwattana Road Pakkred, Nonthaburi 11120 Thailand) as an additional assembly site for the 32Mb MoBL® SRAM 48-Lead TSOP I package. These products are currently processed at Orient Semiconductor Electronics (OSET), a Cypress subcontractor in Taiwan.

The 48-Lead TSOP I package is assembled at OSE, Taiwan and Cypress Bangkok, Thailand using an industry standard set of Bill of Materials (BOM). Please see table below for a comparison of BOM among the assembly sites.

Wafer Fab Site	SkyWater, MN	UMC, Taiwan
Assembly Site	OSE Taiwan	Cypress Bangkok
Leadframe	Cu	Cu
Lead finish	NiPdAu	Pure Sn
Die Attach Material	EM-700J Tape Film / Nitto	DAF HR-9070 / Hitachi
Wire type	0.9mil Au	0.9mil CuPdAu
Mold Compound	CEL9200HF-U / Hitachi	CEL9200HF10-U / Hitachi

Cypress also announces the qualification of new Bill of Materials (BOM) for the 32Mb MoBL® SRAM assembled in the 48-Ball BGA package using the die from UMC's 65-nm wafer fab site. The new mold compound is compatible with industry standard reflow temperatures for applicable package volume, thickness and lead finish. The new bond wire is also consistent with industry standards.

The 48-Ball BGA Pb-free package is assembled at ASE-Kaohsiung (ASE-KH), Taiwan using the following Bill of Materials (BOM):

Wafer Fab Site	SkyWater, MN	UMC, Taiwan
Assembly Site	ASE-KH, Taiwan	ASE-KH, Taiwan
Substrate	BT Laminate	BT Laminate
Solder ball	Sn/Ag/Cu (SAC-405)	Sn/Ag/Cu (SAC-305)
Die Attach Material	D/A1: 2025 / Ablestik D/A2: FH-900 / Hitachi	DAF ATB-125 / Henkel
Wire type	1.0mil Au	0.8mil CuPdAu
Mold Compound	KE-G2270 / Kyocera	KE-G1250AAS / Kyocera

Benefit of Change:
Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Part Numbers Affected: 6
See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:
These assembly sites have been qualified through a series of tests documented in the Qualification Test Plans QTP#192902 (UMC), QTP#190710 (ASE-KH) and QTP#190712 (BKK). These qualification reports can be found as attachments to this PCN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:
Qualification samples may not be built ahead of time for all part numbers affected by this change. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:
Effective 90 days from the date of this notification, all shipments of Commercial, Industrial and Automotive non-PPAP part numbers in the attached file will be supplied from be assembled at BKK, ASE-KH or other approved assembly sites.

Anticipated Impact:
Products fabricated at the new site are completely compatible with existing products from form, fit, functional, parametric and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	Family
1	CY62177EV30LL-55BAXI	ASYNC
2	CY62177EV30LL-55BAXIT	ASYNC
3	CY62177EV30LL-55ZXI	ASYNC
4	CY62177EV30LL-55ZXIT	ASYNC
5	CG8208AA	ASYNC
6	CG8210AA	ASYNC